



SOT687-1

plastic thermal enhanced very thin quad flat package; no leads; 68 terminals; body 10 x 10 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN68; MLF
Package type industry code	HVQFN68; MLF
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	13-6-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.85	-	10	10.15	mm
E	package width	9.85	-	10	10.15	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	68	-	

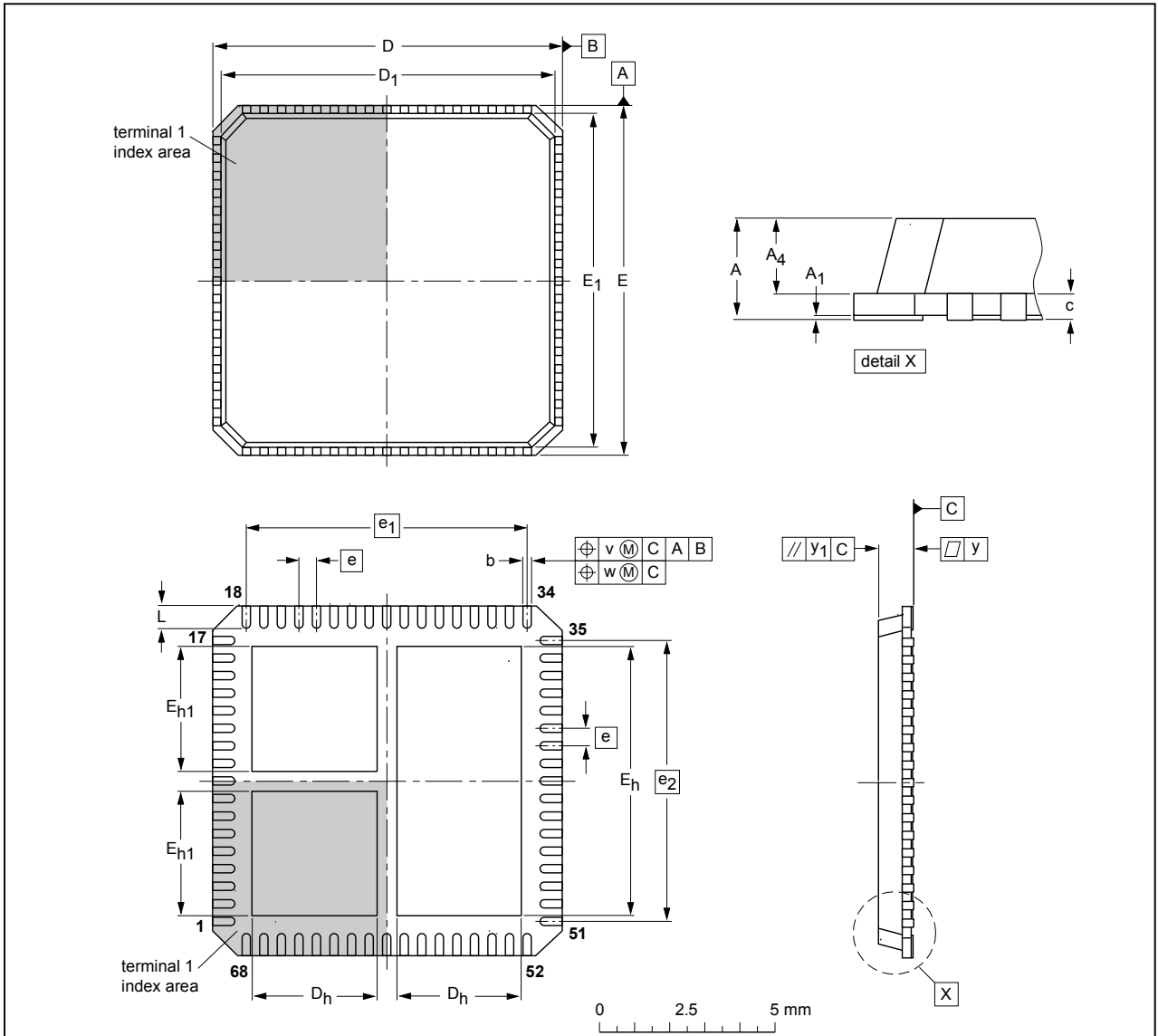


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2. Package outline

HVQFN68: plastic thermal enhanced very thin quad flat package; no leads; 68 terminals; body 10 x 10 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₄	b	c	D	D ₁	D _h	E	E ₁	E _h	E _{h1}	e	e ₁	e ₂	L	v	w	y	y ₁
mm	1	0.05 0.00	0.80 0.65	0.30 0.18	0.2	10.15 9.85	9.95 9.55	3.8 3.5	10.15 9.85	9.95 9.55	7.85 7.55	3.8 3.5	0.5	8	8	0.75 0.50	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT687-1	---	MO-220	---		02-10-18 03-06-13

Fig. 1. Package outline HVQFN68; MLF (SOT687-1)

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3. Soldering

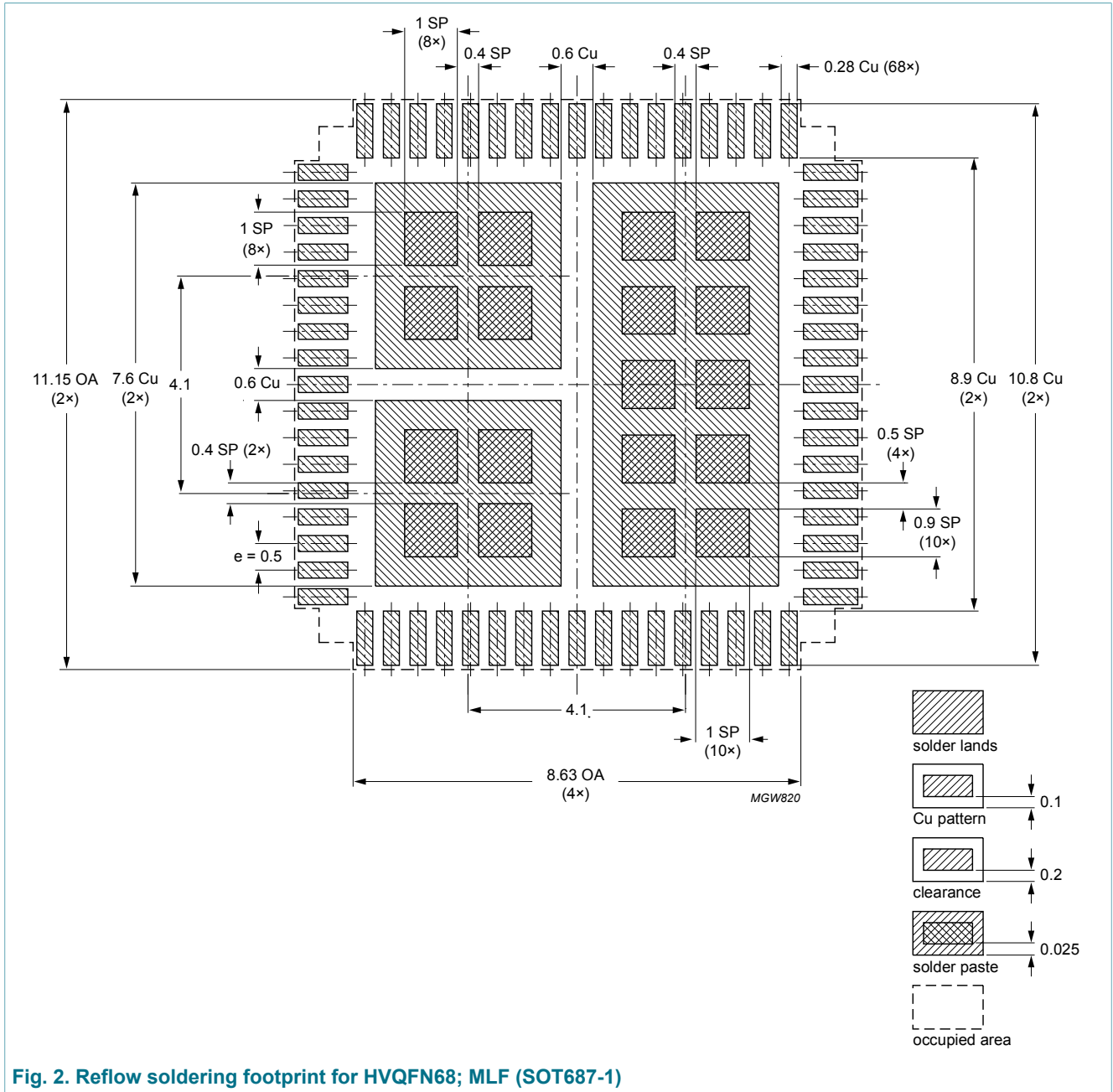


Fig. 2. Reflow soldering footprint for HVQFN68; MLF (SOT687-1)

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4. Legal information

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